

FQB11N40 / FQI11N40

400V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply, electronic lamp ballast based on half bridge.

Features

- 11.4A, 400V, $R_{DS(on)} = 0.48\Omega$ @ $V_{GS} = 10 \text{ V}$
- Low gate charge (typical 27 nC)
- Low Crss (typical 20 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB11N40 / FQI11N40	Units	
V _{DSS}	Drain-Source Voltage		400	V	
I _D	Drain Current - Continuous (T _C = 25°C	C)	11.4	Α	
	- Continuous (T _C = 100	°C)	7.2	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	46	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	520	mJ	
I _{AR}	Avalanche Current	(Note 1)	11.4	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	14.7	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V	
P_{D}	Power Dissipation (T _A = 25°C) *		3.13	W	
	Power Dissipation (T _C = 25°C)		147	W	
	- Derate above 25°C		1.18	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.85	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	400			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.42		V/°C
I _{DSS}	Zana Oala Wallana Busin Oanaal	V _{DS} = 400 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 320 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics		•			
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.7 A		0.38	0.48	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_D = 5.7 \text{ A}$ (Note 4)		7.6		S
C _{oss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		180 20	240 30	pF pF
C _{rss}	<u>'</u>	T = 1.0 MHZ			_	
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 200 V, I _D = 11.4 A,		30	70	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		100	210	ns
t _{d(off)}	Turn-Off Delay Time			60	130	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		60	130	ns
Qg	Total Gate Charge	V _{DS} = 320 V, I _D = 11.4 A,		27	35	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		7.3		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		12.3		nC
	ource Diode Characteristics a	_			11.1	Δ.
l _S	Maximum Continuous Drain-Source Diode Forward Current				11.4	A
I _{SM}	Maximum Pulsed Drain-Source Diode F				46	A V
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 11.4 A			1.5	-
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 11.4 \text{ A,}$ $dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)		240		ns
Q _{rr}	Reverse Recovery Charge	ui _F / ut = 100 A/μs (1000 4)		1.8		μC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 7mH, I_{AS} = 11.4A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 11.4A, di/dt \leq 200A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

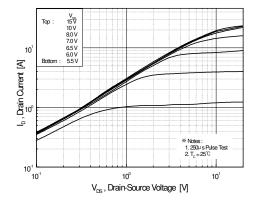


Figure 1. On-Region Characteristics

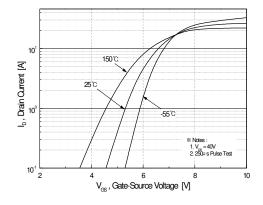


Figure 2. Transfer Characteristics

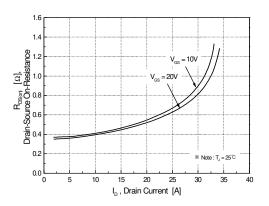


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

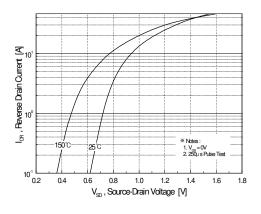


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

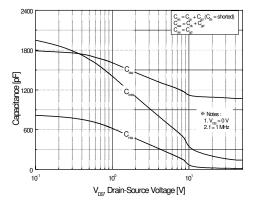


Figure 5. Capacitance Characteristics

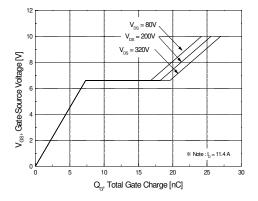


Figure 6. Gate Charge Characteristics

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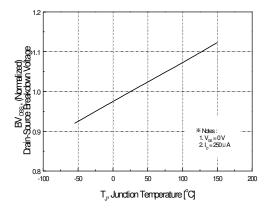
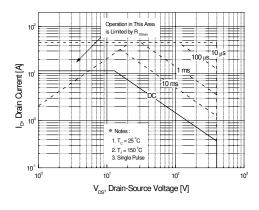


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



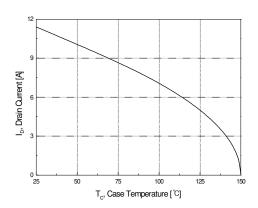


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

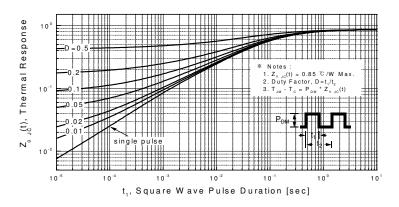
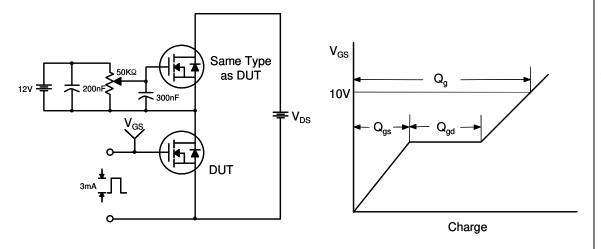


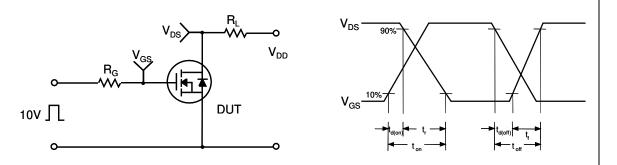
Figure 11. Transient Thermal Response Curve

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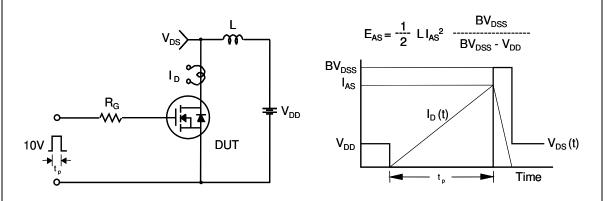
Gate Charge Test Circuit & Waveform



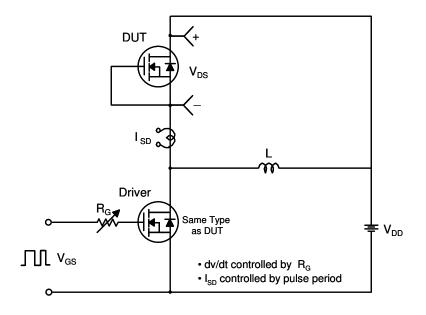
Resistive Switching Test Circuit & Waveforms

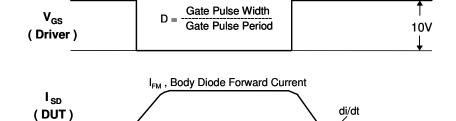


Unclamped Inductive Switching Test Circuit & Waveforms



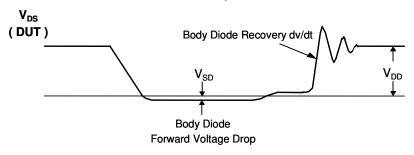
Peak Diode Recovery dv/dt Test Circuit & Waveforms



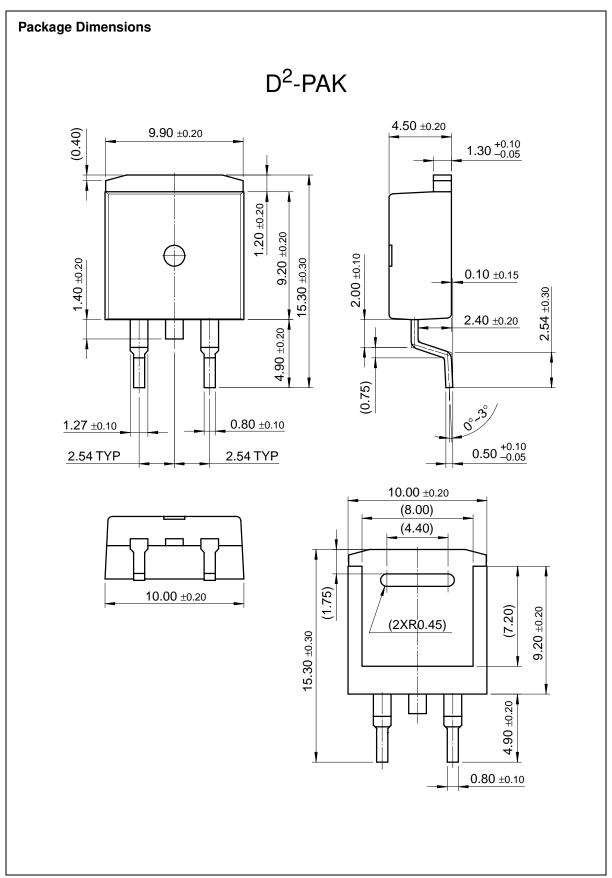


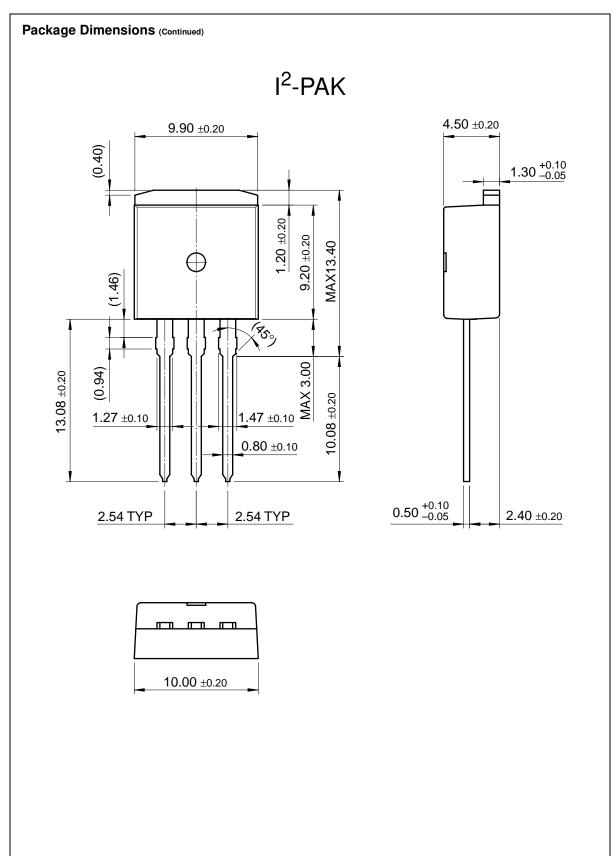
Body Diode Reverse Current

 I_{RM}



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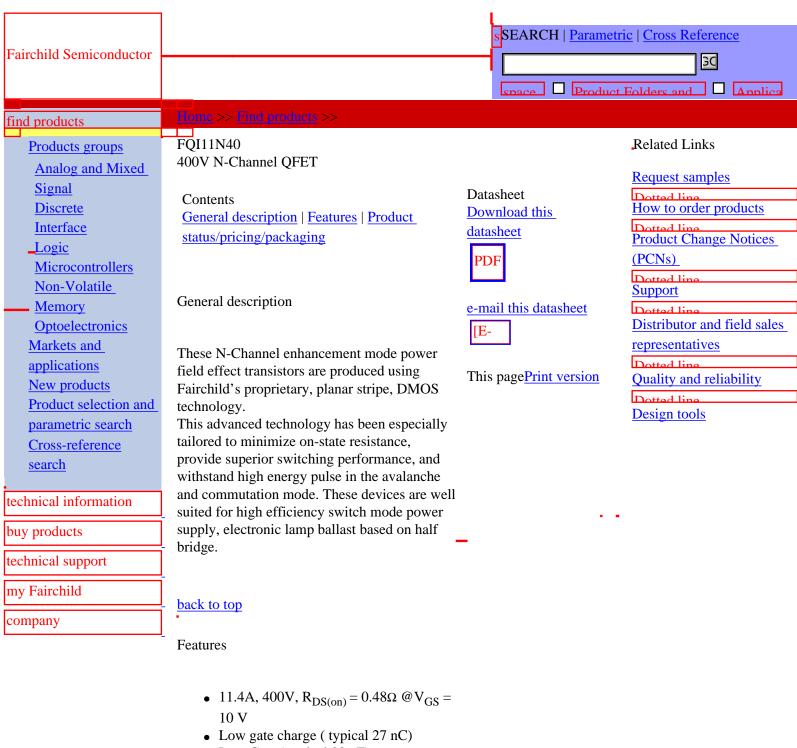
Product	Product status	Pricing*	Package type	Leads	Packing method
FQB11N40TM	Full Production	\$1.27	TO-263(D2PAK)	2	TAPE REEL

* 1,000 piece Budgetary Pricing

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- Low Crss (typical 20 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQI11N40TU	Full Production	\$1.27	TO-262(I2PAK)	3	RAIL

* 1,000 piece Budgetary Pricing

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